Appl. No.: 10/534,617

Docket No.: DB001183-000

Amdt. Dated: 10/4/2010

Reply to Office action of May 3, 2010

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (previously presented)

A method of manufacturing a security thread or strip introduceable in banknotes, said security

thread or strip having a microchip, comprising the steps of:

providing a support material on a substrate to form a thread or strip;

softening said support material, by heating said support material;

depositing a microchip on or at least partly in the softened support material; and

curing said support material, by cooling said support material.

Claim 2 (previously presented)

The method of manufacturing a security thread according to claim 1, wherein said support

material is at least one of a heat-sensitive material, a thermoplastic material containing a resin having a

low melting point, a wax, a vinyl-polymer, a polyurethane or any polymer or compound distributed in

water based solvents or in any solvent that has the characteristics to modify its state from solid to soft.

Claim 3 (previously presented)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

softening said support material, the support material is heated by at least one of contact with a heating

means, by heat radiation, by an infrared beam, by ultraviolet beam and by laser beam.

Claim 4 (previously presented)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

depositing said microchip, the microchip falls on the softened support material and sinks at least partly

into the support material by its own gravity.

{01148205}

-2-

Appl. No.: 10/534,617

Docket No.: DB001183-000

Amdt. Dated: 10/4/2010

Reply to Office action of May 3, 2010

Claim 5 (previously presented)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

depositing said support chip, said microchip is positioned on the support material, and thereafter, when

the support material is still soft, the microchip is pressed into the support material by a pressing means.

Claim 6 (previously presented)

The method of manufacturing a security thread according to claim 1, comprising a step of

winding up the security thread around a spool.

Claim 7 (previously presented)

The method of manufacturing a security thread according to claim 6, wherein a timing of

softening said support material, depositing said microchip and/or curing said support material is set in

accordance to a winding operation of the spool.

Claim 8 (previously presented)

The method of manufacturing a security thread according to claim 6 or claim 7, wherein said

spool is a watermarking cylinder which has register notches and transports the security thread into a paper

compound, and said timing of softening said support material, depositing said microchip and/or curing

said support material is set in accordance to a detection of said register notches.

Claims 9-17 (cancelled)

{01148205}

-3-